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Part Number: [0738001200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End Option, 144 Circuits

Documents:

3D Model	Packaging Specification PK-70873-0868 (PDF)
Drawing (PDF)	Test Summary TS-73670-990-001 (PDF)
3D Model (PDF)	RoHS Certificate of Compliance (PDF)
Product Specification PS-73780-999-001 (PDF)	

Agency Certification

CSA	LR19980
UL	E29179

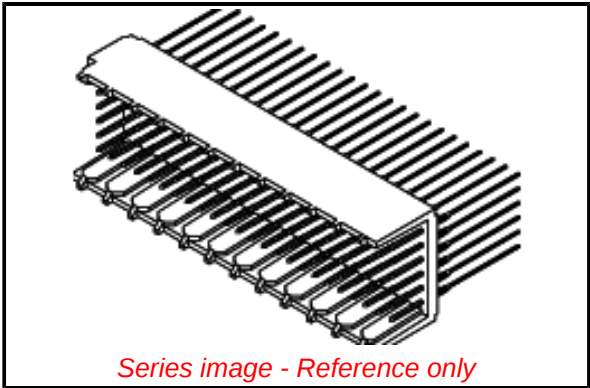
General

Product Family	Backplane Connectors
Series	73800
Application	Midplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800755946383

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	12.000/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	11.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	4.00mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C

Electrical



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

[73800](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard
Receptacle. [73780](#) HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description

Product #

Backplane Insertion Head for 144 Circuits	622005703
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Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Lead-freeProcess Capability	N/A
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0868
Product Specification	PS-73780-999-001
Sales Drawing	SD-73800-001
Test Summary	TS-73670-990-001

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